

2222 Wellington Court Lisle, IL 60532 USA

# **Product Compliance Declaration**

Please see <u>www.molex.com</u> for the most up-to-date information.

Contact Information							
Name	Molex Product Compliance	E-Mail	Product.Compliance@molex.com				
Part Informa	ation						
Part Number	1054051206	Part Weight	0.974903G				
Part Name	Nano Fit SMT R/A Hdr 2X3 Blk 15u'G						

## **Product Composition**

Name	Туре	CAS Number	Proportion (% Total)	Mass (Grams)
Nano Fit SMT R/A Hdr 2X3 Blk 15u'G	Assembly		100	0.974903
Nano Fit SMT R/A Hdr HSG 2X3 Blk	Component		48.2099	0.47
LCP-GF30	Material		48.2099	0.47
Carbon black	Substance	1333-86-4	0.241	0.00235
LCP	Substance		32.7828	0.3196
Further Additives, not to declare	Substance	system	0.7231	0.00705
GF-Fibre	Substance		14.463	0.141
Nano Fit SMT R/A Hdr L TML 15u'G	Assembly		21.5332	0.209928
Nano Fit SMT R/A Hdr L TML w/o plated	Component		18.4634	0.18
Yellow Brass 66% Unplated	Material		18.4634	0.18
Copper	Substance	7440-50-8	12.232	0.11925
Zinc (metal)	Substance	7440-66-6	6.2314	0.06075
NICKEL CROWN ANODE	Material		1.6617	0.0162

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Name	Туре	CAS Number	Proportion (% Total)	Mass (Grams)
Nickel	Substance	7440-02-0	7440-02-0 1.6617	
TIN BALL ANODE	Material		1.2924	0.0126
Tin	Substance	7440-31-5	1.2924	0.0126
Gold Plating	Material		0.1157	0.001128
Cobalt	Substance	7440-48-4	0.0003	0.000003
Nickel	Substance	7440-02-0	0.0003	0.000003
Gold	Substance	7440-57-5	0.1151	0.001122
Nano Fit SMT R/A Hdr S TML 15u'G	Assembly		16.4093	0.159975
Nano Fit SMT R/A Hdr S TML w/o plated	Component		15.3862	0.15
Yellow Brass 66% Unplated	Material		15.3862	0.15
Copper	Substance	7440-50-8	10.1933	0.099375
Zinc (metal)	Substance	7440-66-6	5.1928	0.050625
NICKEL CROWN ANODE	Material		0.5539	0.0054
Nickel	Substance	7440-02-0	0.5539	0.0054
TIN BALL ANODE	Material		0.4308	0.0042
Tin	Substance	7440-31-5	0.4308	0.0042
Gold Plating	Material		0.0385	0.000375
Cobalt	Substance	7440-48-4	1E-04	9E-07
Nickel	Substance	7440-02-0	1E-04	9E-07
Gold	Substance	7440-57-5	0.0383	0.000373
Nano Fit SMT R/A Hdr Clip-S tin	Assembly		13.8475	0.135
Nano Fit SMT R/A Hdr Clip-S w/o plated	Component		12.3089	0.12
Yellow Brass 66% Unplated	Material		12.3089	0.12
Copper	Substance	7440-50-8	8.1547	0.0795
Zinc (metal)	Substance	7440-66-6	4.1543	0.0405
NICKEL CROWN ANODE	Material		0.4718	0.0046
Nickel	Substance	7440-02-0	0.4718	0.0046
TIN BALL ANODE	Material		1.0668	0.0104
Tin	Substance	7440-31-5	1.0668	0.0104

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## **ROHS** Declaration Information

Regulatory Revision EU 2015/863

Compliance Status Compliant

#### **Contained Substances Exceeding Threshold**

None

#### Exemptions

None

## **REACH-SVHC** Declaration Information

Regulatory Revision D(2020)4578-DC (25 June 2020)

#### **Contained Substances Exceeding Threshold**

None

# **GADSL** Declaration Information

Regulatory Revision GADSL imported from IMDS

#### **Contained Substances Exceeding Threshold**

Substance Group	Substance Location	Threshold (PPM)	Concentration (PPM)	Intentionally Added
lead	e-plate Sn (electrodeposited Tin Coatings, bright and matt)	*Note	500	Yes
lead	C2680	*Note	250	Yes
nickel powder [particle diameter < 1 mm]	e-plate Au (Hardgold) (electrodeposited Hardgold	*Note	2,500	Yes
nickel powder [particle diameter < 1 mm]	e-plate Au (Hardgold) (electrodeposited Hardgold	*Note	2,500	Yes
nickel powder [particle diameter < 1 mm]	NICKEL CROWN ANODE	*Note	1,000,000	Yes
nickel powder [particle diameter < 1 mm]	Ep-Ni	*Note	997,500	Yes
Cobalt	e-plate Au (Hardgold) (electrodeposited Hardgold	*Note	2,500	Yes
copper	C2680	*Note	660,000	Yes

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Limitation of this Product Compliance Declaration: This declaration is based on the state of knowledge and belief of Molex as of the date that it is provided. Molex bases its knowledge and belief on information provided by numerous sources, including third parties, and in certain circumstances laboratory test results. Molex has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and substances. Molex represents that to the best of its knowledge that the information provided in this declaration is accurate. Molex's sole liability shall be to either replace the product or refund the purchase price of the product if it does not meet the requirement of this declaration.

Substance Group	Substance Location	Threshold (PPM)	Concentration (PPM)	Intentionally Added
glass, oxide, chemicals	LCP-GF30	*Note	300,000	Yes

\*Note: For GADSL substance declarable/prohibited threshold values, please reference http://www.gadsl.org/

## Exemptions

Part Name	Exemption
e-plate Sn (electrodeposited Tin Coatings, bright and matt)	44 Concentration within acceptable GADSL limits
C2680	44 Concentration within acceptable GADSL limits
e-plate Au (Hardgold) (electrodeposited Hardgold Coatings)	33 Other application (Surface not routinely touched or nickel release rate < 0.5µg/ cm2/week)
e-plate Au (Hardgold) (electrodeposited Hardgold Coatings)	34 Not applicable
NICKEL CROWN ANODE	33 Other application (Surface not routinely touched or nickel release rate < 0.5µg/ cm2/week)
Ep-Ni	33 Other application (Surface not routinely touched or nickel release rate < 0.5µg/ cm2/week)

# **HFLH Declaration Information**

Regulatory Revision IEC 61249-2-21

### **Contained Substances Exceeding Threshold**

None

# **China ROHS Declaration Information**

Part Number1054051206Part NameNano Fit SMT R/A Hdr 2X3 Blk 15u'GPart Information						
				Substance		
Components	Lead	Mercury	Cadmium	Hex. Chromium	PBB	PBDE
Nano Fit SMT R/A Hdr 2X3 Blk 15u'G	0	0	0	0	0	0
Nano Fit SMT R/A Hdr HSG 2X3 Blk	0	0	0	0	0	0
Nano Fit SMT R/A Hdr L TML 15u'G	0	0	0	0	0	0
Nano Fit SMT R/A Hdr L TML w/o plated	0	0	0	0	0	0
Nano Fit SMT R/A Hdr S TML 15u'G	0	0	0	0	0	0

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Components	Lead	Mercury	Cadmium	Hex. Chromium	PBB	PBDE
Nano Fit SMT R/A Hdr S TML w/o plated	0	0	0	0	0	0
Nano Fit SMT R/A Hdr Clip-S tin	0	0	0	0	0	0
Nano Fit SMT R/A Hdr Clip-S w/o plated	0	0	0	0	0	0

# **Process Information**

Component Plating / Surface Finish	N/A
Termination Base Alloy	N/A
Solder Alloy	N/A
Process Capability	N/A
Maximum Exposure Time (seconds)	N/A
Maximum Process Temperature (C)	N/A
Maximum Cycles at Reflow Temperature	N/A
J-STD-020 Moisture Sensitivity Level	N/A

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